

## 200V N-Channel Enhancement Mode MOSFET

### Description

The AP150N20MP uses advanced Trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 12V. This device is suitable for use as a Battery protection or in other Switching application.

### General Features

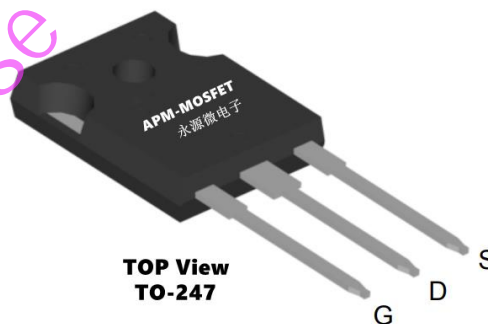
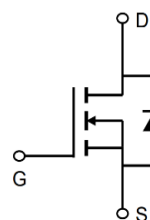
$V_{DS} = 200V$   $I_D = 150A$

$R_{DS(ON)} < 10m\Omega$  @  $V_{GS}=10V$  (Type: 8.5m $\Omega$ )

### Application

UPS

inverter



### Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP150N20MP	TO-247-3L	AP150N20MP XXX YYYY	300

### Absolute Maximum Ratings (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage	200	V
$I_D@T_A=25^\circ C$	Continuous Drain Current $V_{GS} @ 10V$	150	A
$I_D@T_A=70^\circ C$	Continuous Drain Current $V_{GS} @ 10V$	102	A
$I_{DM}^{*1}$	Pulsed Drain Current (pulse width limited by $T_{JM}$ )	450	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 30$	V
EAS	Single Pulse Avalanche Energy	1600	mJ
EAr <sub>a1</sub>	Avalanche Energy, Repetitive	150	mJ
IAR <sub>a1</sub>	Avalanche Current	90	A
$dv/dt^{*2}$	Peak Diode Recovery $dv/dt$	10.0	V/ns
PD	Power Dissipation	750	W
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature Range	150, -55 to 150	°C
TL	Maximum Temperature for Soldering	300	°C
R $\theta$ JC	Thermal Resistance, Junction-to-Case	0.45	°C/W
R $\theta$ JA	Thermal Resistance, Junction-to-Ambient	40	°C/W

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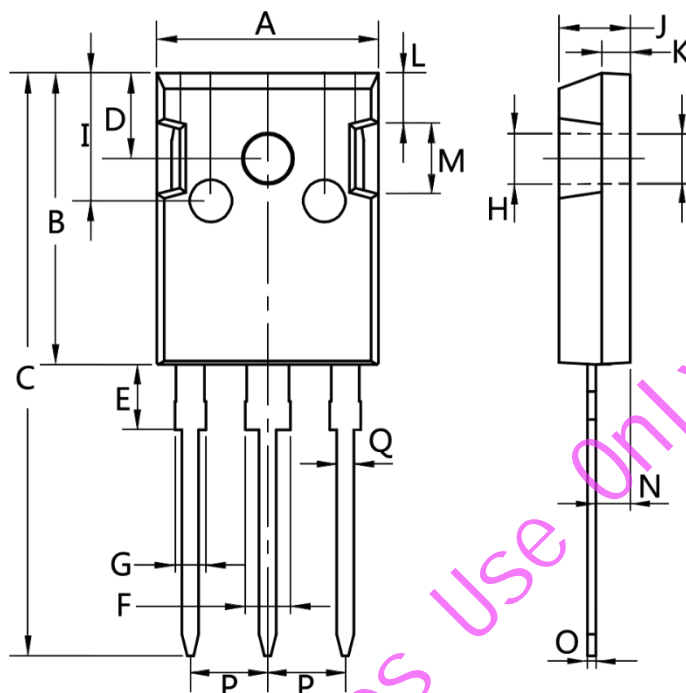
### Electrical Characteristics@T<sub>j</sub>=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
VDSS	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	200	220	--	V
IDSS	Drain to Source Leakage Current	V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>a</sub> =25°C	--	--	1.0	μA
		V <sub>DS</sub> =200V, V <sub>GS</sub> =0V, T <sub>a</sub> =125°C	--	--	100	μA
IGSS(F)	Gate to Source Forward Leakage	V <sub>GS</sub> =+20V	--	--	100	nA
IGSS(R)	Gate to Source Reverse Leakage	V <sub>GS</sub> =-20V	--	--	-100	nA
RDS(ON)	Drain-to-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =80A	--	8.5	10	mΩ
VGS(TH)	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	3.6	4.3	5.0	V
gfs	Forward Trans conductance	V <sub>DS</sub> =25V, I <sub>D</sub> =80A	50	65	--	S
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V V <sub>DS</sub> open f=1.0MHz	--	1.3	--	Ω
Ciss	Input Capacitance	V <sub>GS</sub> =0V V <sub>DS</sub> =25V f=1.0MHz	--	15000	--	pF
Coss	Output Capacitance		--	1000	--	pF
Crss	Reverse Transfer Capacitance		--	420	--	pF
td(ON)	Turn-on Delay Time		--	90	--	ns
t <sub>r</sub>	Rise Time	I <sub>D</sub> =80A, V <sub>DS</sub> =50V V <sub>GS</sub> =10V, R <sub>g</sub> =2.5Ω	--	140	--	ns
td(OFF)	Turn-Off Delay Time		--	220	--	ns
t <sub>f</sub>	Fall Time		--	180	--	ns
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> =80A, V <sub>DD</sub> =100V V <sub>GS</sub> =10V	--	170	--	nC
Q <sub>gs</sub>	Gate to Source Charge		--	30	--	nC
Q <sub>gd</sub>	Gate to Drain ("Miller") Charge		--	50	--	nC
ISD	Continuous Source Current (Body Diode)		--	--	150	A
ISM	Maximum Pulsed Current (Body Diode)		--	--	500	A
VSD	Diode Forward Voltage	I <sub>S</sub> =80A, V <sub>GS</sub> =0V	--	--	1.2	V
trr	Reverse Recovery Time	I <sub>S</sub> =60A, T <sub>j</sub> =25°C, V <sub>DD</sub> =50V dI <sub>F</sub> /dt=100A/μs, V <sub>GS</sub> =0V	--	220	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge		--	1.1	--	uC

#### Note :

- 1、The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width ≅ 300us , duty cycle ≅ 2%
- 3、The EAS data shows Max. rating . The test condition is T<sub>J</sub> = 25°C, L = 0.3mH, R<sub>G</sub> = 25Ω, V<sub>DD</sub>=50V, V<sub>GS</sub>=10V a2
- 4、The I<sub>SD</sub>=80A, di/dt≤100A/us, V<sub>DD</sub>≤BV<sub>DS</sub>, Start T<sub>J</sub>=25°C
- 5、The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

### Package Mechanical Data-TO-247-3L



Dim.	Min.	Max.
A	15.0	16.0
B	20.0	21.0
C	41.0	42.0
D	5.0	6.0
E	4.0	5.0
F	2.5	3.5
G	1.75	2.5
H	3.0	3.5
I	8.0	10.0
J	4.9	5.1
K	1.9	2.1
L	3.5	4.0
M	4.75	5.25
N	2.0	3.0
O	0.55	0.75
P	Typ 5.08	
Q	1.2	1.3

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Edition	Date	Change
Rve1.0	2020/10/31	Initial release

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